Product data sheet

1. General description

Ultrafast power diode in 2-lead TO220F plastic package.



2. Features and benefits

- Isolated package
- Low forward voltage drop
- Low leakage current
- Soft reverse recovery characteristics
- · High thermal cycling performance
- · Package meets UL94V0 which guaranteed by Epoxy Mold Compound

3. Applications

- Home appliance power supply
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes		Values		Unit
Absolute	maximum rating						
V_{RRM}	repetitive peak reverse voltage			600			V
I _{F(AV)}	average forward current	$δ = 0.5$; square-wave pulse; $T_h \le 80$ °C; Fig. 1; Fig. 2; Fig. 3		8			А
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 μs; $T_h \le 80$ °C; square-wave pulse		16			А
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4		100			А
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse			110		Α
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
V _F	forward voltage	I _F = 8 A; T _j = 25 °C; <u>Fig. 6</u>		-	1.35	1.85	V
		I _F = 8 A; T _j = 150 °C; <u>Fig. 6</u>		-	1.10	1.50	V
Dynamic	characteristics						
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}$; $V_R = 30 \text{ V}$; $dI_F/dt = 100 \text{ A/µs}$; $T_j = 25 \text{ °C}$; Fig. 7		-	24	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		K 1/1 A
2	A	anode	090	K — A 001aaa020
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity		Package issue date
BYV29MFX-600P	TO220F-2L	BYV29MFX-600PQ	Tube	50	TO220Fd-2L	02-Aug-2022

7. Marking

Table 4. Marking codes

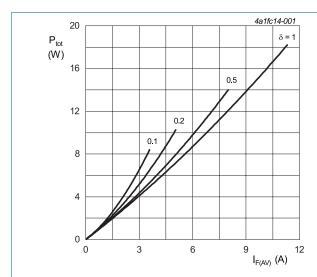
Type number	Marking codes
BYV29MFX-600P	BYV29MFX 600P

8. Limiting values

Table 5. Limiting values

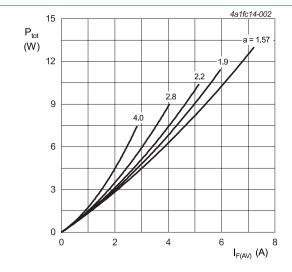
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			600	V
V_{RWM}	crest working reverse voltage			600	V
V_R	reverse voltage	DC		600	V
I _{F(AV)}	average forward current	$δ$ = 0.5; square-wave pulse; $T_h \le 80$ °C; Fig. 1; Fig. 2; Fig. 3		8	А
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _h ≤ 80 °C; square-wave pulse		16	А
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4		100	А
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		110	Α
T _{stg}	storage temperature			-65 to 175	°C
T _j	junction temperature			-65 to 175	°C



$$\begin{split} I_{F(AV)} &= I_{F(RMS)} \times \sqrt{\delta} \\ V_o &= 1.268 \text{ V; } R_s = 0.0301 \text{ } \Omega \end{split}$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor = $I_{F(RMS)}/I_{F(AV)}$ V_o = 1.268 V; R_s = 0.0301 Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

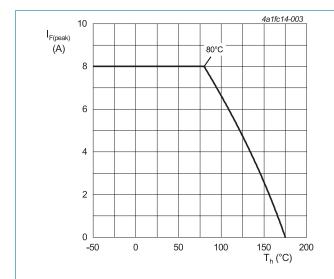


Fig. 3. Forward current as a function of heatsink temperature; maximum values

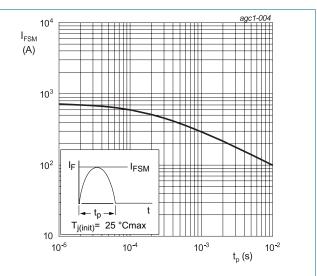
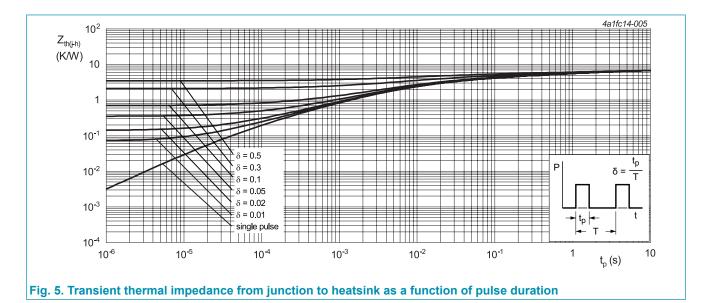


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R _{th(j-h)}	thermal resistance from junction to heatsink	with heatsink compound; Fig. 5		-	-	6.8	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W



10. Isolation characteristics

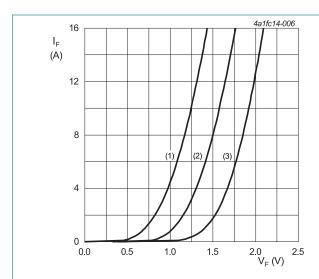
Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
V _{isol(RMS)}	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free		-	-	2500	V
C _{isol}	isolation capacitance	from cathode to external heatsink		-	10	-	pF

11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	aracteristics						
V_{F}	forward current	I _F = 8 A; T _j = 25 °C; <u>Fig. 6</u>		-	1.35	1.85	V
		I _F = 8 A; T _j = 150 °C; <u>Fig. 6</u>		-	1.10	1.50	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C		-	-	8	μA
		V _R = 600 V; T _j = 150 °C		-	-	120	μA
Dynamic	characteristics						
Q _r	reverse charge	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	24	-	nC
t _{rr}	reverse recovery time	$I_F = 0.5 \text{ A}; I_m = 0.25 \text{ A}; I_R = 1 \text{ A}; T_j = 25$ °C		-	28	-	ns
		$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	24	-	ns
I _{RM}	peak reverse recovery current	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	1.9	-	А



 $V_o = 1.268 \text{ V}; R_s = 0.0301 \Omega$

(1) $T_j = 125$ °C; typical values (2) $T_j = 125$ °C; maximum values

(3) $T_i = 25$ °C; maximum values

Fig. 6. Forward current as a function of forward voltage

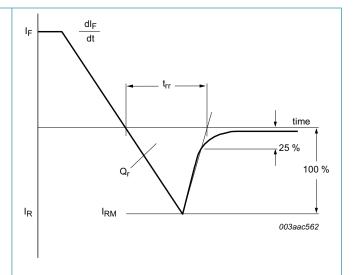
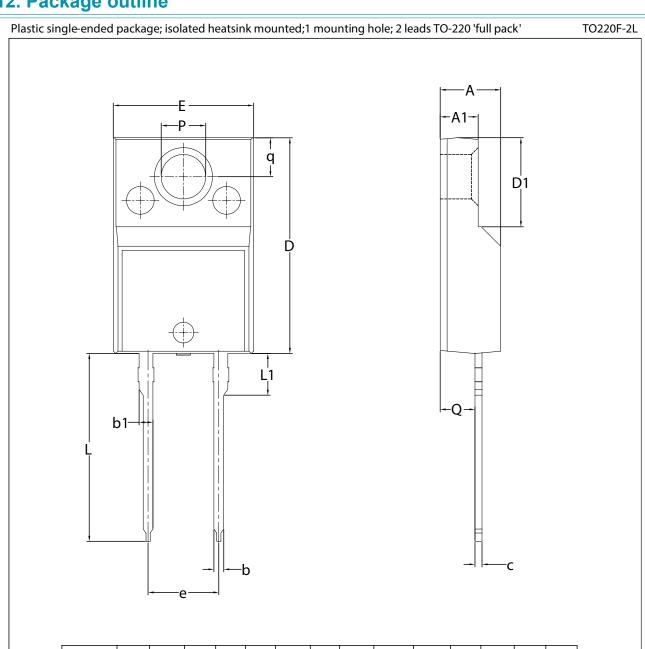


Fig. 7. Reverse recovery definitions; ramp recovery

12. Package outline



Unit		Α	A1	b	b1	С	D	D1	Е	e	L	L1	Р	Q	q
ММ			2.50							5.08	13.50	2.80	3.00	2.30	2.60
IVIIVI	max	4.60	3.10	0.90	1.10	0.70	15.80	6.50	10.30	(BSC)	14.40	3.30	3.40	2.80	3.00

Note:

1. All dimensions don't include mold flash and metal protrusion.

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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14. Contents

1. General description	1
2. Features and benefits	1
3. Applications	1
4. Quick reference data	1
5. Pinning information	2
6. Ordering information	2
7. Marking	2
8. Limiting values	3
9. Thermal characteristics	5
10. Isolation characteristics	5
11. Characteristics	6
12. Package outline	7
13. Legal information	8
14. Contents	10

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